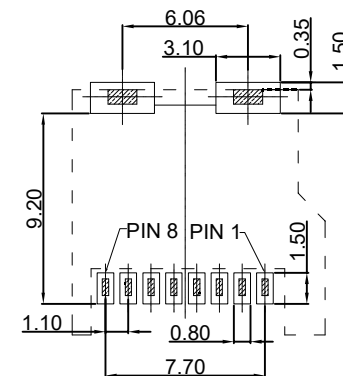
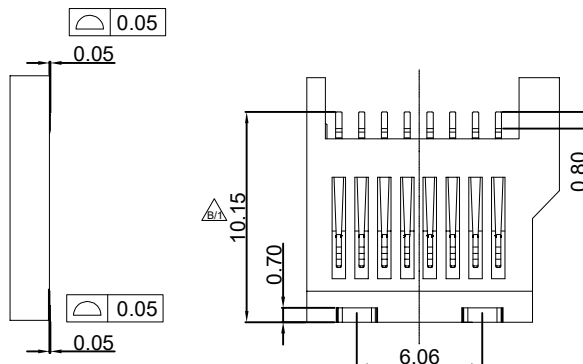
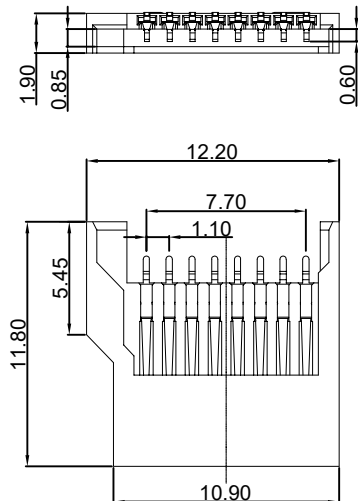


# RoHS

REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2023.11.25



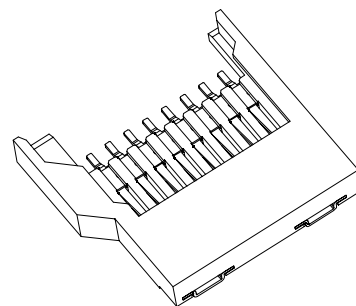
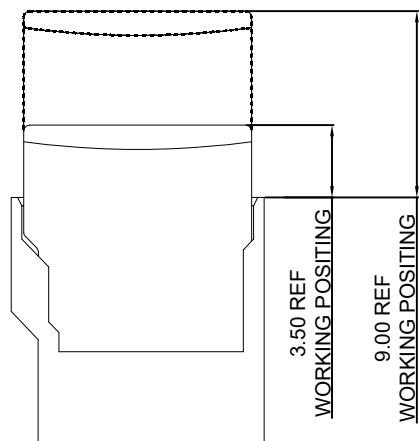
RECOMMENDED PCB HOLE LAYOUT  
COMPONENT SIDE VIEW(TOLERANCE:±0.05)

NOTES:

- MATERIAL:  
HOUSING:HIGH TEMPERATURE THERMOPLASTIC  
UL94V\_0,COLOR:BLACK  
CONTACT:COPPER ALLOYS  
OVER:COPPER ALLOYS OR STEEL
- PLATING:  
UNDERPLATE: NICKEL  
CONTACT AREA: GOLD OVER NICKEL  
SOLDER AREA: TIN OVER NICKEL
- MULTIMEDIA CARD COMPATIBLE

Ordering Code:  
TFN31-S1S1-2000-A  
1 2

- 电镀方式:  
S1=端子镀半金雾锡  
F1=端子镀全金
- 包装方式:  
1=吸塑盘装  
2=载带装



		X. 0.3	X.°±
		. X±0.2	.X°±
		. XX±0.08	.XX°±
		. XXX±0.03	.XXX°±
		UNITS:	mm
PIN NO	NAME	THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF XFCN AND SHALL NOT BE REPRODUCED, COPIED OR CUED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XFCN	
1	DAT2		
2	CD/DAT3		
3	CMD		
4	VDD		
5	CLX		
6	VSS		
7	DATO		
8	DAT1		

PART NO: TFN31-S1S1-2000-A		<b>XFCN</b> 兴飞连接器		
TITLE: T-FLASH 简易全塑卡座		0769-82001899 www.xfconn.com		
		DWG NO: /		
APPD	Chen ZhiQiang	VIEW		
CHKD	Liu Wei	SCALE	SHEET	REV
DRAW	Chen HongJiang	SCALE	1/2	A1
DATE	2024.08.19	NONE		